# **ON Semiconductor**

# Is Now



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# Power MOSFET 30 Amps, 60 Volts

# N-Channel TO-220 and D<sup>2</sup>PAK

Designed for low voltage, high speed switching applications in power supplies, converters and power motor controls and bridge circuits.

#### **Features**

• Pb-Free Packages are Available

#### **Typical Applications**

- Power Supplies
- Converters
- Power Motor Controls
- Bridge Circuits

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	60	Vdc
Drain-to-Gate Voltage ( $R_{GS} = 10 \text{ M}\Omega$ )	$V_{DGR}$	60	Vdc
Gate-to-Source Voltage - Continuous - Non-Repetitive (t <sub>p</sub> ≤10 ms)	V <sub>GS</sub> V <sub>GS</sub>	±20 ±30	Vdc
Drain Current  - Continuous @ $T_A = 25^{\circ}C$ - Continuous @ $T_A = 100^{\circ}C$ - Single Pulse ( $t_p \le 10 \mu s$ )	I <sub>D</sub> I <sub>D</sub>	27 15 80	Adc Apk
Total Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	88.2 0.59	W W/°C
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
	E <sub>AS</sub>	101	mJ
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.7	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8 in from case for 10 seconds	TL	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

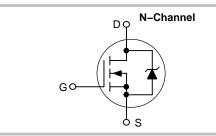


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# 30 AMPERES, 60 VOLTS

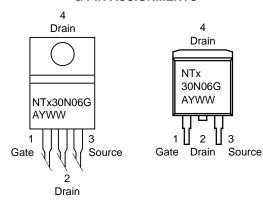
 $R_{DS(on)} = 42 \text{ m}\Omega$ 







# MARKING DIAGRAMS & PIN ASSIGNMENTS



NTx30N06 = Device Code x = B or P

A = Assembly Location
 Y = Year
 WW = Work Week
 G = Pb-Free Package

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>.I</sub> = 25°C unless otherwise noted)

	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Drain-to-Source Breakdown (V <sub>GS</sub> = 0 Vdc, I <sub>D</sub> = 250 μAd Temperature Coefficient (Posi	V <sub>(BR)DSS</sub>	60 -	71.1 70	-	Vdc mV/°C	
Zero Gate Voltage Drain Curro $(V_{DS} = 60 \text{ Vdc}, V_{GS} = 0 \text{ Vdc})$ $(V_{DS} = 60 \text{ Vdc}, V_{GS} = 0 \text{ Vdc})$	I <sub>DSS</sub>	_ _	- -	1.0 10	μAdc	
Gate-Body Leakage Current	I <sub>GSS</sub>	_	_	±100	nAdc	
ON CHARACTERISTICS (Note	1)					
Gate Threshold Voltage (Note $(V_{DS} = V_{GS}, I_D = 250 \mu Adc)$ Threshold Temperature Coeffi	V <sub>GS(th)</sub>	2.0	3.05 7.3	4.0 -	Vdc mV/°C	
Static Drain-to-Source On-R (V <sub>GS</sub> = 10 Vdc, I <sub>D</sub> = 15 Add	R <sub>DS(on)</sub>	_	35	42	mΩ	
Static Drain-to-Source On-V ( $V_{GS} = 10 \text{ Vdc}$ , $I_D = 30 \text{ Adc}$ ( $V_{GS} = 10 \text{ Vdc}$ , $I_D = 15 \text{ Adc}$	V <sub>DS(on)</sub>	_ _	1.1 0.98	1.5 -	Vdc	
Forward Transconductance (N	9FS	_	16	-	mhos	
YNAMIC CHARACTERISTIC	S					
Input Capacitance		C <sub>iss</sub>	_	850	1200	pF
Output Capacitance	$(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0 \text{ Vdc}, $ f = 1.0 MHz)	C <sub>oss</sub>	_	250	350	
Transfer Capacitance	,	C <sub>rss</sub>	_	68	100	
WITCHING CHARACTERIST	ICS (Note 2)					
Turn-On Delay Time		$t_{d(on)}$	_	11	25	ns
Rise Time	(V <sub>DD</sub> = 30 Vdc, I <sub>D</sub> = 30 Adc,	t <sub>r</sub>	_	36	80	
Turn-Off Delay Time	$V_{GS} = 10 \text{ Vdc}, R_G = 9.1 \Omega) \text{ (Note 1)}$	t <sub>d(off)</sub>	_	24	50	
Fall Time		t <sub>f</sub>	_	31	60	
Gate Charge		Q <sub>T</sub>	_	23.4	46	nC
	(V <sub>DS</sub> = 48 Vdc, I <sub>D</sub> = 30 Adc, V <sub>GS</sub> = 10 Vdc) (Note 1)	Q <sub>1</sub>	_	5.1	_	
	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	Q <sub>2</sub>	_	11	ı	
SOURCE-DRAIN DIODE CHA	RACTERISTICS					
Forward On-Voltage	$(I_S = 30 \text{ Adc}, V_{GS} = 0 \text{ Vdc}) \text{ (Note 1)}$ $(I_S = 30 \text{ Adc}, V_{GS} = 0 \text{ Vdc}, T_J = 150^{\circ}\text{C})$	V <sub>SD</sub>		1.03 1.05	1.15 -	Vdc
Reverse Recovery Time		t <sub>rr</sub>	_	52	-	ns
	$(I_S = 30 \text{ Adc}, V_{GS} = 0 \text{ Vdc},$ $dI_S/dt = 100 \text{ A/}\mu\text{s}) \text{ (Note 1)}$	ta	-	38	-	1
	3.5.335., 0,000, (1.0.0.1)	t <sub>b</sub>	-	15	-	1
Reverse Recovery Stored Charge		Q <sub>RR</sub>	_	0.094	_	μС

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

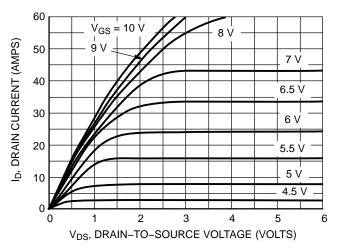


Figure 1. On-Region Characteristics

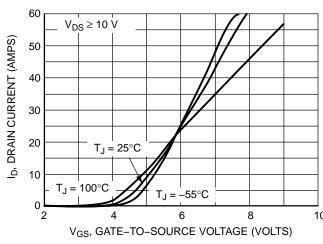


Figure 2. Transfer Characteristics

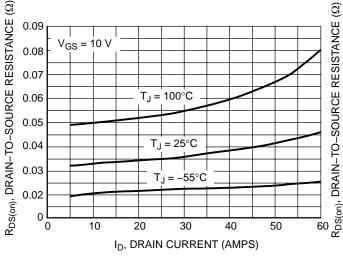


Figure 3. On–Resistance versus Gate–to–Source Voltage

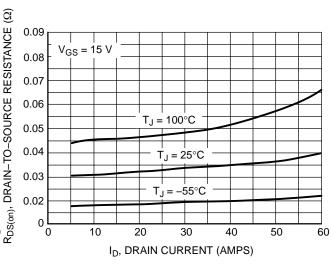


Figure 4. On-Resistance versus Drain Current and Gate Voltage

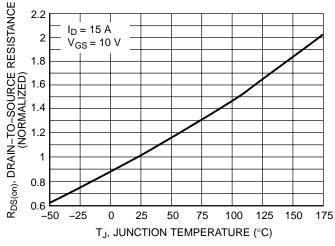


Figure 5. On–Resistance Variation with Temperature

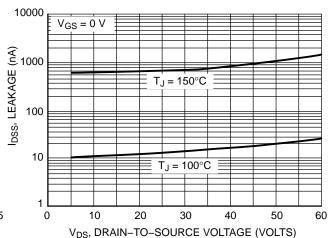


Figure 6. Drain-to-Source Leakage Current versus Voltage

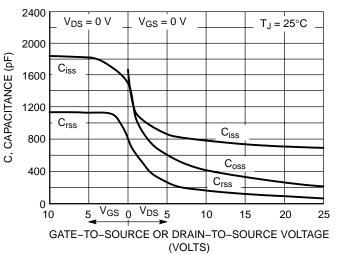


Figure 7. Capacitance Variation

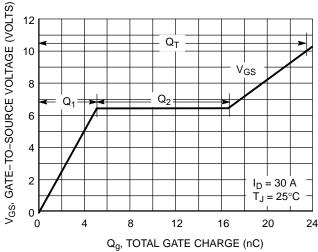


Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

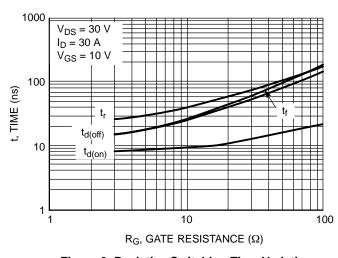


Figure 9. Resistive Switching Time Variation versus Gate Resistance

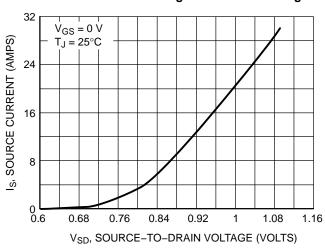


Figure 10. Diode Forward Voltage versus
Current

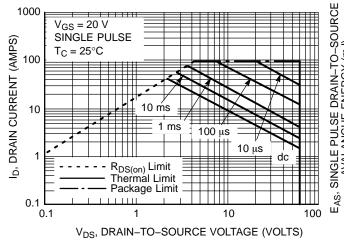


Figure 11. Maximum Rated Forward Biased Safe Operating Area

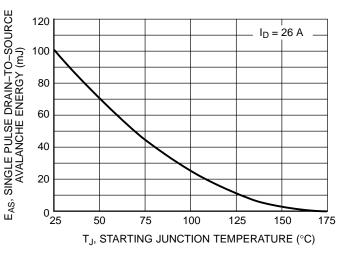


Figure 12. Maximum Avalanche Energy versus Starting Junction Temperature

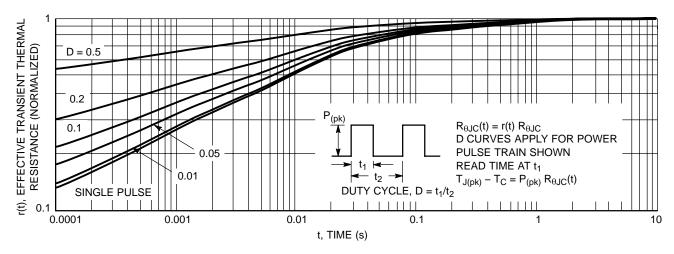


Figure 13. Thermal Response

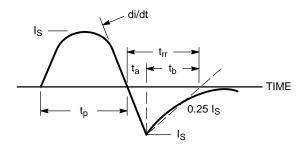


Figure 14. Diode Reverse Recovery Waveform

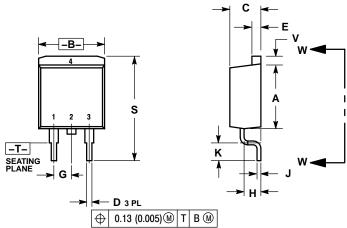
#### **ORDERING INFORMATION**

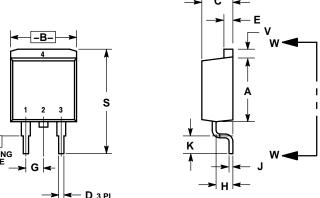
Device	Package	Shipping <sup>†</sup>
NTP30N06	TO-220AB	50 Units / Rail
NTB30N06	D <sup>2</sup> PAK	50 Units / Rail
NTB30N06G	D <sup>2</sup> PAK (Pb-Free)	50 Units / Rail
NTB30N06T4	D <sup>2</sup> PAK	800 Units / Tape & Reel
NTB30N06T4G	D <sup>2</sup> PAK (Pb-Free)	800 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **PACKAGE DIMENSIONS**

#### D<sup>2</sup>PAK CASE 418B-04 **ISSUE J**

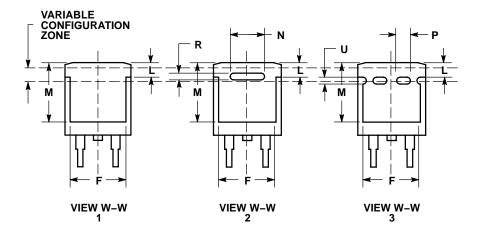




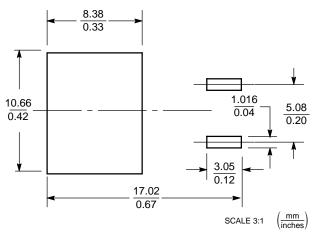
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.340	0.380	8.64	9.65	
В	0.380	0.405	9.65	10.29	
С	0.160	0.190	4.06	4.83	
D	0.020	0.035	0.51	0.89	
Е	0.045	0.055	1.14	1.40	
F	0.310	0.350	7.87	8.89	
G	0.100 BSC		2.54 BSC		
Н	0.080	0.110	2.03	2.79	
J	0.018	0.025	0.46	0.64	
K	0.090	0.110	2.29	2.79	
L	0.052	0.072	1.32	1.83	
М	0.280	0.320	7.11	8.13	
N	0.197 REF		5.00 REF		
Р	0.079 REF		EF 2.00 REF		
R	0.039	REF	0.99 REF		
S	0.575	0.625	14.60	15.88	
v	0.045	0.055	1 14	1 40	

- STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE



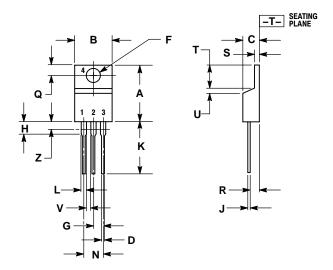
#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AA** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
- CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 5: PIN 1.

GATE DRAIN 2.

3. SOURCE

DRAIN

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